To power the technologies of the future, the world’s most creative companies require innovative solutions to meet demanding design requirements. Cadence is a pivotal leader in electronic systems design, building upon over three decades of computational software expertise to deliver software, hardware, and IP that our customers use to turn design concepts into reality for the most dynamic market applications, including hyperscale computing, 5G communications, automotive, mobile, aerospace, consumer, industrial, and healthcare. We create computational software for Intelligent System Design™.

**Electronic Design**

Cadence offers the broadest, most integrated end-to-end design solutions to help today’s electronic designers do their best work creating tomorrow’s products, for:

- Silicon design creation, simulation, implementation, and signoff of analog and digital circuits; off-the-shelf design IP; and IC packaging
- System design and multiphysics analysis of devices from chips up to smart phones and airplanes; PCB design; and safe and secure embedded software
- Intelligence IP for design of inference processing in edge devices, and machine learning-enhanced tools and machine learning-enabled design flows

**Corporate Facts**

<table>
<thead>
<tr>
<th>Founded</th>
<th>1988</th>
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</thead>
<tbody>
<tr>
<td>Corporate Headquarters</td>
<td>2655 Seely Ave, San Jose, CA 95134 USA</td>
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<tr>
<td>Nasdaq Symbol</td>
<td>CDNS</td>
</tr>
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<td>Primary Business</td>
<td>Computational software for electronic design and system analysis</td>
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Product Offering

Analog and Digital IC Design
As a leader in custom, analog, RF, and mixed-signal design enablement, we provide a complete solution starting with tools and methodologies that enable fast and accurate entry of design concepts all the way through verifying the designs before they are produced in silicon. By selectively automating aspects of custom IC design, we allow engineers to focus on precision-crafting their designs and optimizing circuit performance.

For designing the digital parts of chips, over the past few years we have introduced entirely new, next-generation tools that improve productivity and speed the design process. This comprehensive tool family speeds the full design cycle from front-end design all the way to final silicon signoff convergence.

The Cadence® IP portfolio includes pre-designed and configurable blocks that can be integrated quickly into chip designs, freeing the design team from re-designing these elements. This portfolio includes Tensilica® DSPs for AI, vision, audio, IoT, and baseband applications; Denali® memory and storage IP; and controllers for the latest standard interfaces including PCI Express® (PCI-e®), USB, and Ethernet.

System Verification
The Cadence Verification Suite supports the company’s Intelligent System Design strategy, which enables system and semiconductor companies to create complete, differentiated end products more efficiently. The Verification Suite is comprised of best-in-class core engines, verification fabric technologies, and solutions that increase design quality and throughput, fulfilling verification requirements for a wide variety of applications and vertical segments. This unique mixture of software-based solutions with hardware accelerators delivers the shortest turnaround time and predictable quality. Our technology offers the only proven path for system-level power and signal integrity. We also offer Verification IP (VIP) to verify interface and memory standards.

IC Packaging and PCB Design
We offer the leading IC packaging and PCB design solutions for traditional and advanced 3D-IC solutions. Cadence IC packaging and cross-domain co-design automation provide efficient solutions in system-level co-design and advanced mixed-signal packaging, delivering the automation and accuracy to expedite the design process. Our PCB design solutions enable shorter, more predictable design cycles with greater integration of component design and system-level simulation for a constraint-driven flow for right-first-time design.

Multiphysics and CFD Analysis
Cadence now offers electromagnetic interference (EMI), electromagnetic compliance (EMC), electrothermal, and computational fluid dynamics (CFD) tools. Our solutions include digital twin technology for data center project management. Predicting real-world product performance during the design process is paramount for selecting the optimal design of complex systems.

Molecular Modeling and Biosimulation
Cadence also offers molecular modeling and biosimulation software to improve drug discovery via industry-leading science, efficient algorithms, and cloud-native scalability.

A Great Place to Work
Cadence is committed to being a socially responsible company by building the innovative technologies that transform lives around the world. We pride ourselves on our “One Cadence—One Team” culture that drives our market-and industry-leading innovation and business success. Cadence is recognized as a Great Place to Work around the world, including as one of Fortune Magazine’s “100 Best Companies to Work For” over the last eight years. We have also earned global recognitions for our efforts around our environmental, social, and governance strategies.
Revenue

<table>
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Executive Management

- **Anirudh Devgan, PhD**
  President and Chief Executive Officer

- **Tom Beckley**
  Senior Vice President and General Manager, Custom IC & PCB Group

- **Paul Cunningham, PhD**
  Senior Vice President and General Manager, System Verification Group

- **Tina Jones**
  Senior Vice President, Global Human Resources

- **Nimish Modi**
  Senior Vice President and General Manager, Strategy and New Ventures

- **Karna Nisewaner**
  Corporate Vice President, General Counsel, and Secretary

- **Chin-Chi Teng, PhD**
  Senior Vice President and General Manager, Digital & Signoff Group

- **John Wall**
  Senior Vice President and Chief Financial Officer

- **Neil Zaman**
  Senior Vice President, Worldwide Field Operations

For More Information

Investor Relations: +1.408.944.7100
Media Relations: +1.408.944.7039